

CURABLE RESIN COMPOSITION, PRODUCTION METHOD OF IMAGE SENSOR CHIP
USING THE SAME, AND IMAGE SENSOR CHIP

ABSTRACT

To provide a curable resin composition capable of producing an image sensor chip in which the color shading is suppressed, a production method of image sensor chip using the same, and an image sensor chip.

A curable resin composition which is capable of being coated on a solid-state imaging device substrate and contains a dye having a maximum absorption wavelength in a wavelength range from 600 to 850 nm, a production method of image sensor chip using the same, and an image sensor chip.